



Applications

- Optical planar lightwave circuits
- Multimode optical devices
- Multimode splitter
- Optical interconnections
- Polymer optical bench
- Micro optical elements

Description

The WIR30-RI series are photoactive UV curable resins based on fluorinated acrylate. In particular, they are very useful for optical multimode waveguide device applications such as 1 x n optical splitter and optical interconnections with UV embossing (Imprinting) technology. UV imprinting technology has good advantages for simple fabrication of optical waveguide devices due to the its photolithography and dry etching free process for waveguide patterning. These resins have low optical loss at near 830 and 1310 nm wavelengths, small birefringence, and excellent environmental stability. To obtain the best film quality, a nitrogen environment should beis recommended during the UV exposure time.

Model Number

• WIR series

Features

- UV curing type
- Low optical loss
- Environmental stability

• Controllable refractive index

- Low shrinkage
- Solvent free

Performance Specifications

| Exguide™ | | WIR30-500 | WIR30-480 | WIR30-450 | |
|----------|--|-----------------------|------------------------------------|-----------|-----------|
| Liquide | Viscosity (cps @ 25°C) | | 150 ~ 180 | 180 ~ 240 | 210 ~ 270 |
| | UV-exposure (under N₂) | | > 2,500 mJ/cm² | | |
| | | | (160 ~ 200 °C/30 min, post baking) | | |
| Film | Propagation Loss ⁺ (dB/cm) | $0.83 \mu \mathrm{m}$ | < 0.05 | | |
| | | 1.31 <i>μ</i> m | < 0.11 | | |
| | | 1.55 <i>µ</i> m | < 0.42 | | |
| | Refractive Index @ 1.55μm | | 1.50 | 1.48 | 1.45 |
| | Birefringence (n _™ - n _™) | | 0.001 ± 0.0005 | | |
| | Linear shrinkage (solid to solid) | | < 5% | | |
| | Glass Transition Temp. (Tg) | | Not Detectable | | |
| | Degradation Temp. (1 wt%) | | 310±20°C | | |

- *Measured from slad waveguide (prism coupling method)
- Refractive index is precisely tunable from 1.45 to 1.50 by request.



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Description

The FOWG series are photoactive UV curable resins based on acrylate. They are applicable to flexible optical waveguide devices. UV curing technology has good advantages for simple fabrication of optical waveguide devices due to the its photolithography and dry etching free process for waveguide patterning. These resins have low optical loss at near 830nm wavelength, small birefringence, and excellent environmental stability. To obtain the best film quality, a nitrogen environment should be is recommended during the UV exposure time.

Model Number

FOWG series

Applications

Flexible optical PCB

Features

- UV curing type
- Low optical loss
- Environmental stability
- Low birefringence

Performance Specifications

| | Exguide™ | FOWG-116 | FOWG-115 | |
|---------|---------------------------------------|---|-----------|--|
| Liquide | Viscosity (cps @ 25°C) | 40 ~ 120 | | |
| | UV-exposure (under N₂) | > 1400 mJ/cm²(160°C/30min, post baking) | | |
| | Propagation Loss ⁺ (dB/cm) | < 0.1 dB/cm @ 0.83μm | | |
| | Refractive Index @ 0.83μm | 1.547 | 1.506 | |
| Film | Birefringence (nте - nтм) | < 0.0001 | | |
| | Linear shrinkage (solid to solid) | < 5% | | |
| | Glass Transition Temp. (Tg) | 30 ~ 50℃ | | |
| | Degradation Temp. (1 wt%) | 280 ± 20℃ | 270 ± 20℃ | |

- *Measured from slad waveguide (prism coupling method)